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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	896
Number of Logic Elements/Cells	8064
Total RAM Bits	368640
Number of I/O	311
Number of Gates	400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	400-BGA
Supplier Device Package	400-FBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s400a-5fgg400c

Introduction

The Spartan®-3A family of Field-Programmable Gate Arrays (FPGAs) solves the design challenges in most high-volume, cost-sensitive, I/O-intensive electronic applications. The five-member family offers densities ranging from 50,000 to 1.4 million system gates, as shown in [Table 1](#).

The Spartan-3A FPGAs are part of the Extended Spartan-3A family, which also include the non-volatile Spartan-3AN and the higher density Spartan-3A DSP FPGAs. The Spartan-3A family builds on the success of the earlier Spartan-3E and Spartan-3 FPGA families. New features improve system performance and reduce the cost of configuration. These Spartan-3A family enhancements, combined with proven 90 nm process technology, deliver more functionality and bandwidth per dollar than ever before, setting the new standard in the programmable logic industry.

Because of their exceptionally low cost, Spartan-3A FPGAs are ideally suited to a wide range of consumer electronics applications, including broadband access, home networking, display/projection, and digital television equipment.

The Spartan-3A family is a superior alternative to mask programmed ASICs. FPGAs avoid the high initial cost, lengthy development cycles, and the inherent inflexibility of conventional ASICs, and permit field design upgrades.

Features

- Very low cost, high-performance logic solution for high-volume, cost-conscious applications
- Dual-range V_{CCAUX} supply simplifies 3.3V-only design
- Suspend, Hibernate modes reduce system power
- Multi-voltage, multi-standard SelectIO™ interface pins
 - Up to 502 I/O pins or 227 differential signal pairs
 - LVCMS, LVTTI, HSTL, and SSTL single-ended I/O
 - 3.3V, 2.5V, 1.8V, 1.5V, and 1.2V signaling
 - Selectable output drive, up to 24 mA per pin
 - QUIETIO standard reduces I/O switching noise
 - Full $3.3V \pm 10\%$ compatibility and hot swap compliance

- 640+ Mb/s data transfer rate per differential I/O
- LVDS, RSDS, mini-LVDS, HSTL/SSTL differential I/O with integrated differential termination resistors
- Enhanced Double Data Rate (DDR) support
- DDR/DDR2 SDRAM support up to 400 Mb/s
- Fully compliant 32-/64-bit, 33/66 MHz PCI® technology support
- Abundant, flexible logic resources
 - Densities up to 25,344 logic cells, including optional shift register or distributed RAM support
 - Efficient wide multiplexers, wide logic
 - Fast look-ahead carry logic
 - Enhanced 18×18 multipliers with optional pipeline
 - IEEE 1149.1/1532 JTAG programming/debug port
- Hierarchical SelectRAM™ memory architecture
 - Up to 576 Kbits of fast block RAM with byte write enables for processor applications
 - Up to 176 Kbits of efficient distributed RAM
- Up to eight Digital Clock Managers (DCMs)
 - Clock skew elimination (delay locked loop)
 - Frequency synthesis, multiplication, division
 - High-resolution phase shifting
 - Wide frequency range (5 MHz to over 320 MHz)
- Eight low-skew global clock networks, eight additional clocks per half device, plus abundant low-skew routing
- Configuration interface to industry-standard PROMs
 - Low-cost, space-saving SPI serial Flash PROM
 - x8 or x8/x16 BPI parallel NOR Flash PROM
 - Low-cost Xilinx® [Platform Flash](#) with JTAG
 - Unique Device DNA identifier for design authentication
 - Load multiple bitstreams under FPGA control
 - Post-configuration CRC checking
- Complete Xilinx [ISE](#)® and [WebPACK](#)™ development system software support plus [Spartan-3A Starter Kit](#)
- [MicroBlaze](#)™ and [PicoBlaze](#)™ embedded processors
- Low-cost QFP and BGA packaging, Pb-free options
 - Common footprints support easy density migration
 - Compatible with select [Spartan-3AN](#) nonvolatile FPGAs
 - Compatible with higher density [Spartan-3A DSP](#) FPGAs
- [XA Automotive](#) version available

Table 1: Summary of Spartan-3A FPGA Attributes

Device	System Gates	Equivalent Logic Cells	CLB Array (One CLB = Four Slices)				Distributed RAM bits ⁽¹⁾	Block RAM bits ⁽¹⁾	Dedicated Multipliers	DCMs	Maximum User I/O	Maximum Differential I/O Pairs
			Rows	Columns	CLBs	Slices						
XC3S50A	50K	1,584	16	12	176	704	11K	54K	3	2	144	64
XC3S200A	200K	4,032	32	16	448	1,792	28K	288K	16	4	248	112
XC3S400A	400K	8,064	40	24	896	3,584	56K	360K	20	4	311	142
XC3S700A	700K	13,248	48	32	1,472	5,888	92K	360K	20	8	372	165
XC3S1400A	1400K	25,344	72	40	2,816	11,264	176K	576K	32	8	502	227

Notes:

- By convention, one Kb is equivalent to 1,024 bits.

Spartan-3A FPGA Design Documentation

The functionality of the Spartan®-3A FPGA Family is described in the following documents. The topics covered in each guide is listed below.

- **DS706: Extended Spartan-3A Family Overview**
www.xilinx.com/support/documentation/data_sheets/ds706.pdf
- **UG331: Spartan-3 Generation FPGA User Guide**
www.xilinx.com/support/documentation/user_guides/ug331.pdf
 - Clocking Resources
 - Digital Clock Managers (DCMs)
 - Block RAM
 - Configurable Logic Blocks (CLBs)
 - Distributed RAM
 - SRL16 Shift Registers
 - Carry and Arithmetic Logic
 - I/O Resources
 - Embedded Multiplier Blocks
 - Programmable Interconnect
 - ISE® Software Design Tools
 - IP Cores
 - Embedded Processing and Control Solutions
 - Pin Types and Package Overview
 - Package Drawings
 - Powering FPGAs
 - Power Management
- **UG332: Spartan-3 Generation Configuration User Guide**
www.xilinx.com/support/documentation/user_guides/ug332.pdf
 - Configuration Overview
 - Configuration Pins and Behavior
 - Bitstream Sizes

- Detailed Descriptions by Mode
 - Master Serial Mode using Xilinx® Platform Flash PROM
 - Master SPI Mode using Commodity SPI Serial Flash PROM
 - Master BPI Mode using Commodity Parallel NOR Flash PROM
 - Slave Parallel (SelectMAP) using a Processor
 - Slave Serial using a Processor
 - JTAG Mode
- ISE iMPACT Programming Examples
- MultiBoot Reconfiguration
- Design Authentication using Device DNA

For application examples, see the Spartan-3A FPGA application notes.

- **Spartan-3A FPGA Application Notes**
www.xilinx.com/support/documentation/spartan-3a_application_notes.htm

For specific hardware examples, please see the Spartan-3A FPGA Starter Kit board web page, which has links to various design examples and the user guide.

- **Spartan-3A/3AN FPGA Starter Kit Board Page**
www.xilinx.com/s3astarter
- **UG334: Spartan-3A/3AN FPGA Starter Kit User Guide**
www.xilinx.com/support/documentation/boards_and_kits/ug334.pdf

For information on the XA Automotive version of the Spartan-3A family, see the following data sheet.

- XA Spartan-3A Automotive FPGA Family Data Sheet
www.xilinx.com/support/documentation/data_sheets/ds681.pdf

Create a Xilinx user account and sign up to receive automatic e-mail notification whenever this data sheet or the associated user guides are updated.

- Sign Up for Alerts
www.xilinx.com/support/answers/18683.htm

Table 12: DC Characteristics of User I/Os Using Single-Ended Standards

IOSTANDARD Attribute	Test Conditions		Logic Level Characteristics		
	I _{OL} (mA)	I _{OH} (mA)	V _{OL} Max (V)	V _{OH} Min (V)	
LVTTL ⁽³⁾	2	2	-2	0.4	2.4
	4	4	-4		
	6	6	-6		
	8	8	-8		
	12	12	-12		
	16	16	-16		
	24	24	-24		
LVCMOS33 ⁽³⁾	2	2	-2	0.4	V _{CCO} - 0.4
	4	4	-4		
	6	6	-6		
	8	8	-8		
	12	12	-12		
	16	16	-16		
	24 ⁽⁴⁾	24	-24		
LVCMOS25 ⁽³⁾	2	2	-2	0.4	V _{CCO} - 0.4
	4	4	-4		
	6	6	-6		
	8	8	-8		
	12	12	-12		
	16 ⁽⁴⁾	16	-16		
	24 ⁽⁴⁾	24	-24		
LVCMOS18 ⁽³⁾	2	2	-2	0.4	V _{CCO} - 0.4
	4	4	-4		
	6	6	-6		
	8	8	-8		
	12 ⁽⁴⁾	12	-12		
	16 ⁽⁴⁾	16	-16		
LVCMOS15 ⁽³⁾	2	2	-2	0.4	V _{CCO} - 0.4
	4	4	-4		
	6	6	-6		
	8 ⁽⁴⁾	8	-8		
	12 ⁽⁴⁾	12	-12		
LVCMOS12 ⁽³⁾	2	2	-2	0.4	V _{CCO} - 0.4
	4 ⁽⁴⁾	4	-4		
	6 ⁽⁴⁾	6	-6		

Table 12: DC Characteristics of User I/Os Using Single-Ended Standards(Continued)

IOSTANDARD Attribute	Test Conditions		Logic Level Characteristics	
	I _{OL} (mA)	I _{OH} (mA)	V _{OL} Max (V)	V _{OH} Min (V)
PCI33_3 ⁽⁵⁾	1.5	-0.5	10% V _{CCO}	90% V _{CCO}
PCI66_3 ⁽⁵⁾	1.5	-0.5	10% V _{CCO}	90% V _{CCO}
HSTL_I ⁽⁴⁾	8	-8	0.4	V _{CCO} - 0.4
HSTL_III ⁽⁴⁾	24	-8	0.4	V _{CCO} - 0.4
HSTL_I_18	8	-8	0.4	V _{CCO} - 0.4
HSTL_II_18 ⁽⁴⁾	16	-16	0.4	V _{CCO} - 0.4
HSTL_III_18	24	-8	0.4	V _{CCO} - 0.4
SSTL18_I	6.7	-6.7	V _{TT} - 0.475	V _{TT} + 0.475
SSTL18_II ⁽⁴⁾	13.4	-13.4	V _{TT} - 0.603	V _{TT} + 0.603
SSTL2_I	8.1	-8.1	V _{TT} - 0.61	V _{TT} + 0.61
SSTL2_II ⁽⁴⁾	16.2	-16.2	V _{TT} - 0.81	V _{TT} + 0.81
SSTL3_I	8	-8	V _{TT} - 0.6	V _{TT} + 0.6
SSTL3_II	16	-16	V _{TT} - 0.8	V _{TT} + 0.8

Notes:

- The numbers in this table are based on the conditions set forth in [Table 8](#) and [Table 11](#).
- Descriptions of the symbols used in this table are as follows:
 I_{OL} — the output current condition under which V_{OL} is tested
 I_{OH} — the output current condition under which V_{OH} is tested
 V_{OL} — the output voltage that indicates a Low logic level
 V_{OH} — the output voltage that indicates a High logic level
 V_{CCO} — the supply voltage for output drivers
 V_{TT} — the voltage applied to a resistor termination
- For the LVCMOS and LVTTL standards; the same V_{OL} and V_{OH} limits apply for the Fast, Slow, and QUIETIO slew attributes.
- These higher-drive output standards are supported only on FPGA banks 1 and 3. Inputs are unrestricted. See the chapter "Using I/O Resources" in [UG331](#).
- Tested according to the relevant PCI specifications. For information on PCI IP solutions, see www.xilinx.com/pci. The PCIX IOSTANDARD is available and has equivalent characteristics but no PCI-X IP is supported.

Input Setup and Hold Times

Table 20: Setup and Hold Times for the IOB Input Path

Symbol	Description	Conditions	IFD_DELAY_VALUE	Device	Speed Grade		Units
					-5	-4	
					Min	Min	
Setup Times							
T _{IOPICK}	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). No Input Delay is programmed.	LVCMOS25 ⁽²⁾	0	XC3S50A	1.56	1.58	ns
				XC3S200A	1.71	1.81	ns
				XC3S400A	1.30	1.51	ns
				XC3S700A	1.34	1.51	ns
				XC3S1400A	1.36	1.74	ns
T _{IOPICKD}	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). The Input Delay is programmed.	LVCMOS25 ⁽²⁾	1	XC3S50A	2.16	2.18	ns
			2		3.10	3.12	ns
			3		3.51	3.76	ns
			4		4.04	4.32	ns
			5		3.88	4.24	ns
			6		4.72	5.09	ns
			7		5.47	5.94	ns
			8		5.97	6.52	ns
			1	XC3S200A	2.05	2.20	ns
			2		2.72	2.93	ns
			3		3.38	3.78	ns
			4		3.88	4.37	ns
			5		3.69	4.20	ns
			6		4.56	5.23	ns
			7		5.34	6.11	ns
			8		5.85	6.71	ns
			1	XC3S400A	1.79	2.02	ns
			2		2.43	2.67	ns
			3		3.02	3.43	ns
			4		3.49	3.96	ns
			5		3.41	3.95	ns
			6		4.20	4.81	ns
			7		4.96	5.66	ns
			8		5.44	6.19	ns

Table 22: Propagation Times for the IOB Input Path(Continued)

Symbol	Description	Conditions	DELAY_VALUE	Device	Speed Grade		Units
					-5	-4	
					Max	Max	
T_{IOPLID}	The time it takes for data to travel from the Input pin through the IFF latch to the I output with the input delay programmed	LVCMOS25 ⁽²⁾	5	XC3S400A	3.55	4.18	ns
			6		4.34	5.03	ns
			7		5.09	5.88	ns
			8		5.58	6.42	ns
			1	XC3S700A	1.96	2.18	ns
			2		2.76	3.06	ns
			3		3.45	3.95	ns
			4		3.97	4.54	ns
			5	XC3S1400A	3.83	4.37	ns
			6		4.74	5.42	ns
			7		5.53	6.33	ns
			8		6.06	6.96	ns
			1		1.93	2.40	ns
			2		2.69	3.15	ns
			3		3.52	3.99	ns
			4		3.89	4.55	ns
			5		3.95	4.42	ns
			6		4.53	5.32	ns
			7		5.30	6.21	ns
			8		5.83	6.80	ns

Notes:

1. The numbers in this table are tested using the methodology presented in [Table 27](#) and are based on the operating conditions set forth in [Table 8](#) and [Table 11](#).
2. This propagation time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the data Input. When this is true, add the appropriate Input adjustment from [Table 23](#).

Output Timing Adjustments

Table 26: Output Timing Adjustments for IOB

		Add the Adjustment Below		Units	
		Speed Grade			
		-5	-4		
Convert Output Time from LVC MOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)					
LV TTL	Slow	2 mA	5.58	5.58	ns
		4 mA	3.16	3.16	ns
		6 mA	3.17	3.17	ns
		8 mA	2.09	2.09	ns
		12 mA	1.62	1.62	ns
		16 mA	1.24	1.24	ns
		24 mA	2.74 ⁽³⁾	2.74 ⁽³⁾	ns
	Fast	2 mA	3.03	3.03	ns
		4 mA	1.71	1.71	ns
		6 mA	1.71	1.71	ns
		8 mA	0.53	0.53	ns
		12 mA	0.53	0.53	ns
		16 mA	0.59	0.59	ns
		24 mA	0.60	0.60	ns
QuietIO	QuietIO	2 mA	27.67	27.67	ns
		4 mA	27.67	27.67	ns
		6 mA	27.67	27.67	ns
		8 mA	16.71	16.71	ns
		12 mA	16.67	16.67	ns
		16 mA	16.22	16.22	ns
		24 mA	12.11	12.11	ns

Table 26: Output Timing Adjustments for IOB(Continued)

		Add the Adjustment Below		Units	
		Speed Grade			
		-5	-4		
Convert Output Time from LVC MOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)					
LVC MOS33	Slow	2 mA	5.58	5.58	
		4 mA	3.17	3.17	
		6 mA	3.17	3.17	
		8 mA	2.09	2.09	
		12 mA	1.24	1.24	
		16 mA	1.15	1.15	
		24 mA	2.55 ⁽³⁾	2.55 ⁽³⁾	
	Fast	2 mA	3.02	3.02	
		4 mA	1.71	1.71	
		6 mA	1.72	1.72	
		8 mA	0.53	0.53	
		12 mA	0.59	0.59	
		16 mA	0.59	0.59	
		24 mA	0.51	0.51	
QuietIO	QuietIO	2 mA	27.67	27.67	
		4 mA	27.67	27.67	
		6 mA	27.67	27.67	
		8 mA	16.71	16.71	
		12 mA	16.29	16.29	
		16 mA	16.18	16.18	
		24 mA	12.11	12.11	

Table 26: Output Timing Adjustments for IOB(Continued)

Convert Output Time from LVCMS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)			Add the Adjustment Below		Units	
			Speed Grade			
	-5	-4				
LVCMS25	Slow	2 mA	5.33	5.33	ns	
		4 mA	2.81	2.81	ns	
		6 mA	2.82	2.82	ns	
		8 mA	1.14	1.14	ns	
		12 mA	1.10	1.10	ns	
		16 mA	0.83	0.83	ns	
		24 mA	2.26 ⁽³⁾	2.26 ⁽³⁾	ns	
	Fast	2 mA	4.36	4.36	ns	
		4 mA	1.76	1.76	ns	
		6 mA	1.25	1.25	ns	
		8 mA	0.38	0.38	ns	
		12 mA	0	0	ns	
		16 mA	0.01	0.01	ns	
		24 mA	0.01	0.01	ns	
	QuietIO	2 mA	25.92	25.92	ns	
		4 mA	25.92	25.92	ns	
		6 mA	25.92	25.92	ns	
		8 mA	15.57	15.57	ns	
		12 mA	15.59	15.59	ns	
		16 mA	14.27	14.27	ns	
		24 mA	11.37	11.37	ns	
LVCMS18	Slow	2 mA	4.48	4.48	ns	
		4 mA	3.69	3.69	ns	
		6 mA	2.91	2.91	ns	
		8 mA	1.99	1.99	ns	
		12 mA	1.57	1.57	ns	
		16 mA	1.19	1.19	ns	
	Fast	2 mA	3.96	3.96	ns	
		4 mA	2.57	2.57	ns	
		6 mA	1.90	1.90	ns	
		8 mA	1.06	1.06	ns	
		12 mA	0.83	0.83	ns	
		16 mA	0.63	0.63	ns	
	QuietIO	2 mA	24.97	24.97	ns	
		4 mA	24.97	24.97	ns	
		6 mA	24.08	24.08	ns	
		8 mA	16.43	16.43	ns	
		12 mA	14.52	14.52	ns	
		16 mA	13.41	13.41	ns	

Table 26: Output Timing Adjustments for IOB(Continued)

Convert Output Time from LVCMS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)			Add the Adjustment Below		Units	
			Speed Grade			
	-5	-4				
LVCMS15	Slow	2 mA	5.82	5.82	ns	
		4 mA	3.97	3.97	ns	
		6 mA	3.21	3.21	ns	
		8 mA	2.53	2.53	ns	
		12 mA	2.06	2.06	ns	
		2 mA	5.23	5.23	ns	
		4 mA	3.05	3.05	ns	
	Fast	6 mA	1.95	1.95	ns	
		8 mA	1.60	1.60	ns	
		12 mA	1.30	1.30	ns	
		2 mA	34.11	34.11	ns	
		4 mA	25.66	25.66	ns	
		6 mA	24.64	24.64	ns	
		8 mA	22.06	22.06	ns	
	QuietIO	12 mA	20.64	20.64	ns	
		2 mA	7.14	7.14	ns	
		4 mA	4.87	4.87	ns	
		6 mA	5.67	5.67	ns	
		2 mA	6.77	6.77	ns	
		4 mA	5.02	5.02	ns	
		6 mA	4.09	4.09	ns	
LVCMS12	Slow	2 mA	50.76	50.76	ns	
		4 mA	43.17	43.17	ns	
		6 mA	37.31	37.31	ns	
		PCI33_3	0.34	0.34	ns	
		PCI66_3	0.34	0.34	ns	
		HSTL_I	0.78	0.78	ns	
	Fast	HSTL_III	1.16	1.16	ns	
		HSTL_I_18	0.35	0.35	ns	
		HSTL_II_18	0.30	0.30	ns	
		HSTL_III_18	0.47	0.47	ns	
		SSTL18_I	0.40	0.40	ns	
		SSTL18_II	0.30	0.30	ns	
	QuietIO	SSTL2_I	0	0	ns	
		SSTL2_II	-0.05	-0.05	ns	
		SSTL3_I	0	0	ns	
		SSTL3_II	0.17	0.17	ns	

Digital Frequency Synthesizer (DFS)

Table 38: Recommended Operating Conditions for the DFS

Symbol	Description	Speed Grade				Units	
		-5		-4			
		Min	Max	Min	Max		
Input Frequency Ranges⁽²⁾							
F _{CLKIN}	CLKIN_FREQ_FX	Frequency for the CLKIN input	0.200	333 ⁽⁴⁾	0.200	333 ⁽⁴⁾ MHz	
Input Clock Jitter Tolerance⁽³⁾							
CLKIN_CYC_JITT_FX_LF	Cycle-to-cycle jitter at the CLKIN input, based on CLKFX output frequency	F _{CLKFX} ≤ 150 MHz	–	±300	–	±300 ps	
CLKIN_CYC_JITT_FX_HF		F _{CLKFX} > 150 MHz	–	±150	–	±150 ps	
CLKIN_PER_JITT_FX	Period jitter at the CLKIN input	–	±1	–	±1	ns	

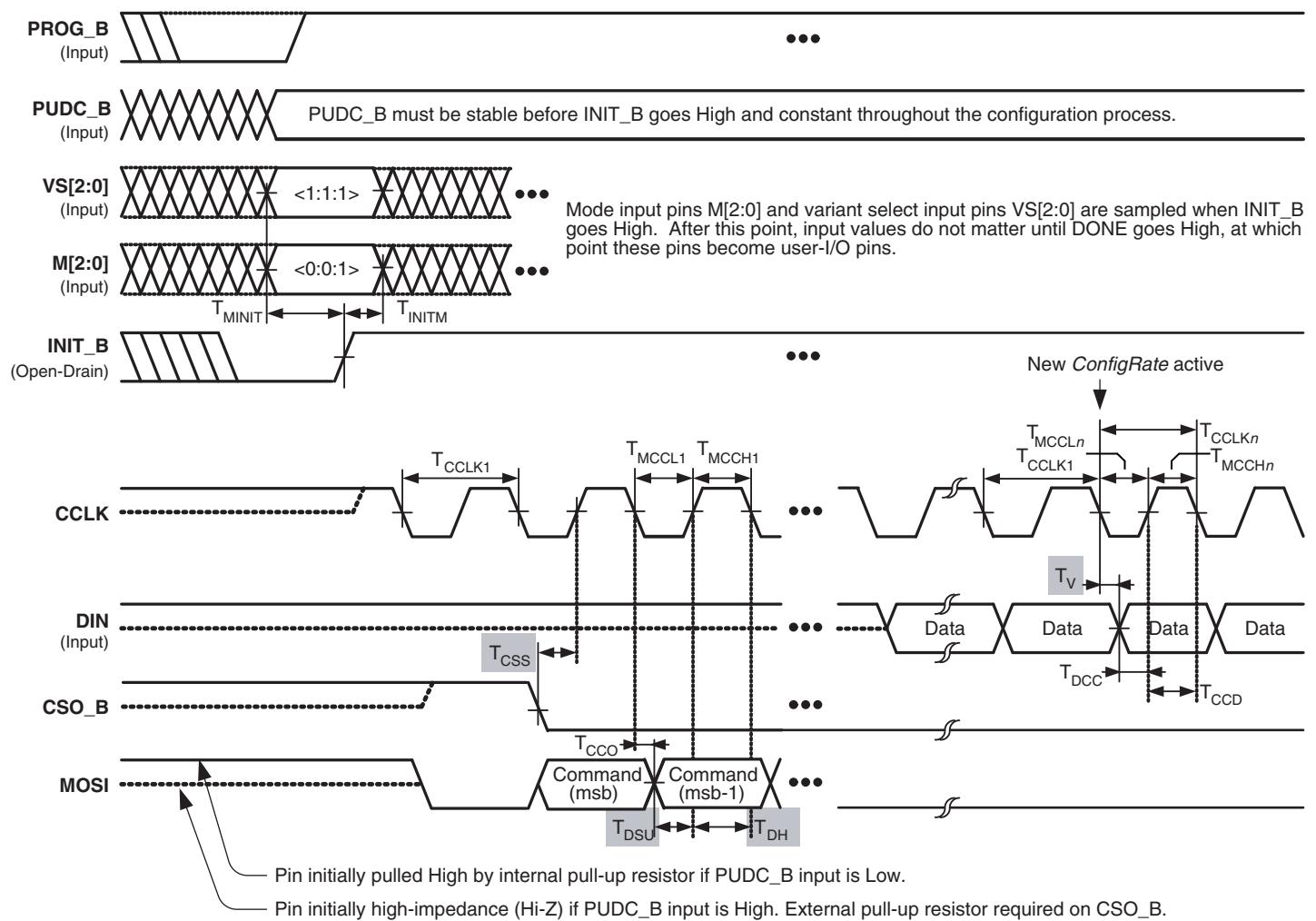
Notes:

1. DFS specifications apply when either of the DFS outputs (CLKFX or CLKFX180) are used.
2. If both DFS and DLL outputs are used on the same DCM, follow the more restrictive CLKIN_FREQ_DLL specifications in [Table 36](#).
3. CLKIN input jitter beyond these limits may cause the DCM to lose lock.
4. To support double the maximum effective FCLKIN limit, set the CLKIN_DIVIDE_BY_2 attribute to TRUE. This attribute divides the incoming clock frequency by two as it enters the DCM.

Table 39: Switching Characteristics for the DFS

Symbol	Description	Device	Speed Grade				Units	
			-5		-4			
			Min	Max	Min	Max		
Output Frequency Ranges								
CLKOUT_FREQ_FX ⁽²⁾	Frequency for the CLKFX and CLKFX180 outputs	All	5	350	5	320	MHz	
Output Clock Jitter^(3,4)								
CLKOUT_PER_JITT_FX	Period jitter at the CLKFX and CLKFX180 outputs.	All	Typ	Max	Typ	Max		
			Use the Spartan-3A Jitter Calculator: www.xilinx.com/support/documentation/data_sheets/s3a_jitter_calc.zip				ps	
			±[1% of CLKFX period + 100]	±[1% of CLKFX period + 200]	±[1% of CLKFX period + 100]	±[1% of CLKFX period + 200]	ps	
Duty Cycle^(5,6)								
CLKOUT_DUTY_CYCLE_FX	Duty cycle precision for the CLKFX and CLKFX180 outputs, including the BUFGMUX and clock tree duty-cycle distortion	All	–	±[1% of CLKFX period + 350]	–	±[1% of CLKFX period + 350]	ps	
Phase Alignment⁽⁶⁾								
CLKOUT_PHASE_FX	Phase offset between the DFS CLKFX output and the DLL CLK0 output when both the DFS and DLL are used	All	–	±200	–	±200	ps	
CLKOUT_PHASE_FX180	Phase offset between the DFS CLKFX180 output and the DLL CLK0 output when both the DFS and DLL are used	All	–	±[1% of CLKFX period + 200]	–	±[1% of CLKFX period + 200]	ps	

Serial Peripheral Interface (SPI) Configuration Timing



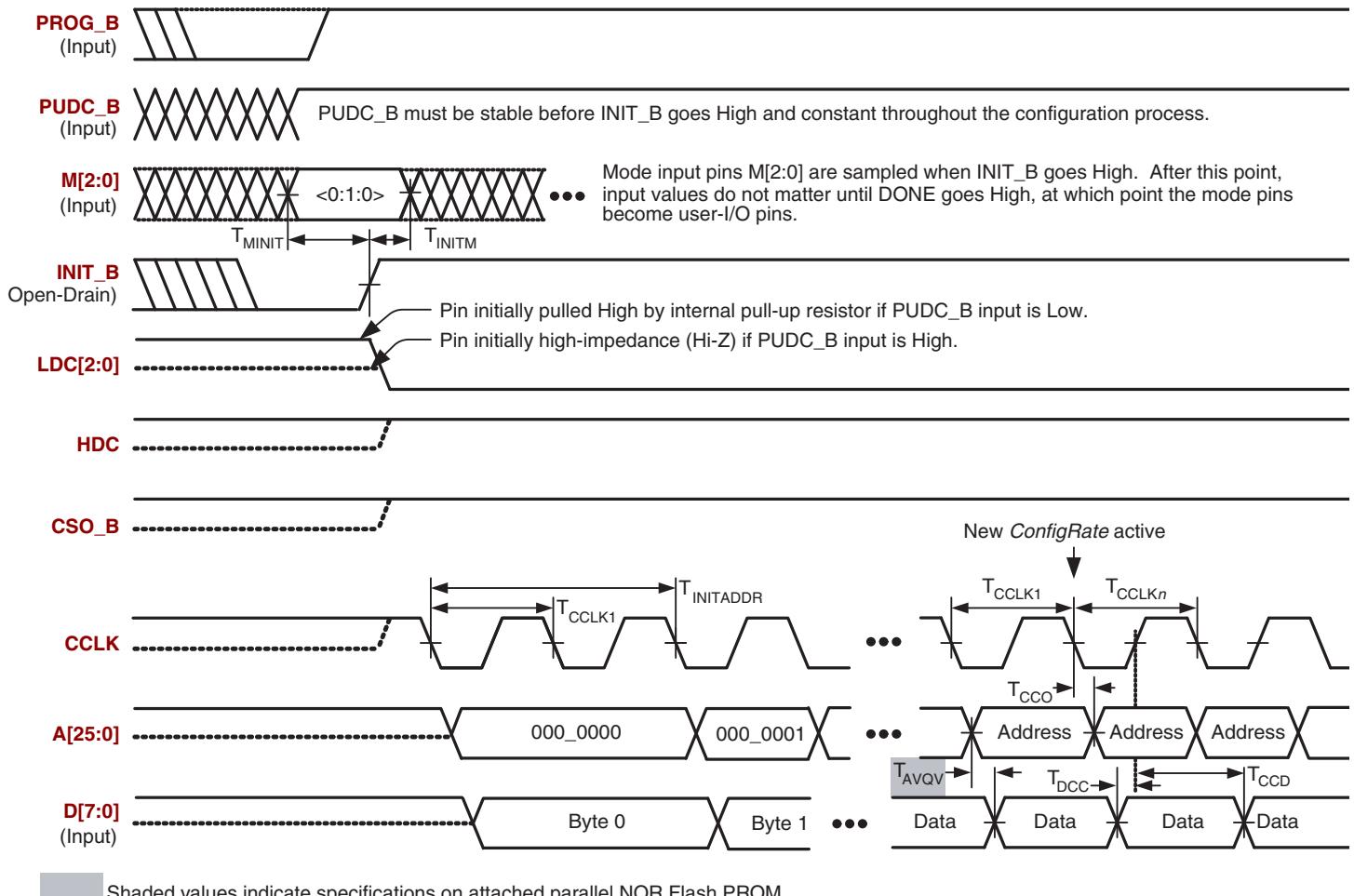
DS529-3_06_102506

Figure 14: Waveforms for Serial Peripheral Interface (SPI) Configuration

Table 52: Timing for Serial Peripheral Interface (SPI) Configuration Mode

Symbol	Description	Minimum	Maximum	Units
T_{CCLK1}	Initial CCLK clock period			See Table 46
T_{CCLKn}	CCLK clock period after FPGA loads ConfigRate bitstream option setting			See Table 46
T_{MINIT}	Setup time on VS[2:0] variant-select pins and M[2:0] mode pins before the rising edge of INIT_B	50	–	ns
T_{INITM}	Hold time on VS[2:0] variant-select pins and M[2:0] mode pins after the rising edge of INIT_B	0	–	ns
T_{CCO}	MOSI output valid delay after CCLK falling clock edge			See Table 50
T_{DCC}	Setup time on the DIN data input before CCLK rising clock edge			See Table 50
T_{CCD}	Hold time on the DIN data input after CCLK rising clock edge			See Table 50

Byte Peripheral Interface (BPI) Configuration Timing



Shaded values indicate specifications on attached parallel NOR Flash PROM.

DS529-3_05_021009

Figure 15: Waveforms for Byte-wide Peripheral Interface (BPI) Configuration

Table 54: Timing for Byte-wide Peripheral Interface (BPI) Configuration Mode

Symbol	Description	Minimum	Maximum	Units
T _{CCLK1}	Initial CCLK clock period			See Table 46
T _{CCLKn}	CCLK clock period after FPGA loads ConfigRate setting			See Table 46
T _{MINIT}	Setup time on M[2:0] mode pins before the rising edge of INIT_B	50	—	ns
T _{INITM}	Hold time on M[2:0] mode pins after the rising edge of INIT_B	0	—	ns
T _{INITADDR}	Minimum period of initial A[25:0] address cycle; LDC[2:0] and HDC are asserted and valid	5	5	T _{CCLK1} cycles
T _{CCO}	Address A[25:0] outputs valid after CCLK falling edge			See Table 50
T _{DCC}	Setup time on D[7:0] data inputs before CCLK rising edge			See T _{SMDCC} in Table 51
T _{CCD}	Hold time on D[7:0] data inputs after CCLK rising edge	0	—	ns

Table 57: Types of Pins on Spartan-3A FPGAs(Continued)

Type / Color Code	Description	Pin Name(s) in Type
PWR MGMT	Control and status pins for the power-saving Suspend mode. SUSPEND is a dedicated pin and is powered by V _{CCAUX} . AWAKE is a dual-purpose pin. Unless Suspend mode is enabled in the application, AWAKE is available as a user-I/O pin.	SUSPEND, AWAKE
JTAG	Dedicated JTAG pin - 4 per device. Not available as a user-I/O pin. Every package has four dedicated JTAG pins. These pins are powered by V _{CCAUX} .	TDI, TMS, TCK, TDO
GND	Dedicated ground pin. The number of GND pins depends on the package used. All must be connected.	GND
V _{CCAUX}	Dedicated auxiliary power supply pin. The number of V _{CCAUX} pins depends on the package used. All must be connected. V _{CCAUX} can be either 2.5V or 3.3V. Set on board and using CONFIG V _{CCAUX} constraint.	V _{CCAUX}
V _{CINT}	Dedicated internal core logic power supply pin. The number of V _{CINT} pins depends on the package used. All must be connected to +1.2V.	V _{CINT}
V _{CCO}	Along with all the other V _{CCO} pins in the same bank, this pin supplies power to the output buffers within the I/O bank and sets the input threshold voltage for some I/O standards. All must be connected.	V _{CCO} _#
N.C.	This package pin is not connected in this specific device/package combination but may be connected in larger devices in the same package.	N.C.

Notes:

- # = I/O bank number, an integer between 0 and 3.

Package Pins by Type

Each package has three separate voltage supply inputs—V_{CINT}, V_{CCAUX}, and V_{CCO}—and a common ground return, GND. The numbers of pins dedicated to these functions vary by package, as shown in Table 58.

Table 58: Power and Ground Supply Pins by Package

Package	V _{CINT}	V _{CCAUX}	V _{CCO}	GND
VQ100	4	3	6	13
TQ144	4	4	8	13
FT256 (50A/200A/400A)	6	4	16	28
FT256 (700A/1400A)	15	10	13	50
FG320	6	8	16	32
FG400	9	8	22	43
FG484	15	10	24	53
FG676	23	14	36	77

A majority of package pins are user-defined I/O or input pins. However, the numbers and characteristics of these I/O depend on the device type and the package in which it is available, as shown in Table 59. The table shows the maximum number of single-ended I/O pins available, assuming that all I/O-, INPUT-, DUAL-, VREF-, and CLK-type pins are used as general-purpose I/O. AWAKE is counted here as a dual-purpose I/O pin. Likewise, the table shows the maximum number of differential pin-pairs available on the package. Finally, the table shows how the total maximum user-I/Os are distributed by pin type, including the number of unconnected—N.C.—pins on the device.

Not all I/O standards are supported on all I/O banks. The left and right banks (I/O banks 1 and 3) support higher output drive current than the top and bottom banks (I/O banks 0 and 2). Similarly, true differential output standards, such as LVDS, RSDS, PPDS, miniLVDS, and TMDS, are only supported in the top or bottom banks (I/O banks 0 and 2). Inputs are unrestricted. For more details, see the chapter “Using I/O Resources” in [UG331](#).

Table 66: Spartan-3A TQ144 Pinout(Continued)

Bank	Pin Name	Pin	Type
2	IO_L05P_2	P46	I/O
2	IO_L06N_2/D6	P49	DUAL
2	IO_L06P_2	P47	I/O
2	IO_L07N_2/D4	P51	DUAL
2	IO_L07P_2/D5	P50	DUAL
2	IO_L08N_2/GCLK15	P55	GCLK
2	IO_L08P_2/GCLK14	P54	GCLK
2	IO_L09N_2/GCLK1	P59	GCLK
2	IO_L09P_2/GCLK0	P57	GCLK
2	IO_L10N_2/GCLK3	P60	GCLK
2	IO_L10P_2/GCLK2	P58	GCLK
2	IO_L11N_2/DOUT	P64	DUAL
2	IO_L11P_2/AWAKE	P63	PWR MGMT
2	IO_L12N_2/D3	P68	DUAL
2	IO_L12P_2/INIT_B	P67	DUAL
2	IO_L13N_2/D0/DIN/MISO	P71	DUAL
2	IO_L13P_2/D2	P69	DUAL
2	IO_L14N_2/CCLK	P72	DUAL
2	IO_L14P_2/D1	P70	DUAL
2	IP_2/VREF_2	P53	VREF
2	VCCO_2	P40	VCCO
2	VCCO_2	P61	VCCO
3	IO_L01N_3	P6	I/O
3	IO_L01P_3	P4	I/O
3	IO_L02N_3	P5	I/O
3	IO_L02P_3	P3	I/O
3	IO_L03N_3	P8	I/O
3	IO_L03P_3	P7	I/O
3	IO_L04N_3/VREF_3	P11	VREF
3	IO_L04P_3	P10	I/O
3	IO_L05N_3/LHCLK1	P13	LHCLK
3	IO_L05P_3/LHCLK0	P12	LHCLK
3	IO_L06N_3/IRDY2/LHCLK3	P16	LHCLK
3	IO_L06P_3/LHCLK2	P15	LHCLK
3	IO_L07N_3/LHCLK5	P20	LHCLK
3	IO_L07P_3/LHCLK4	P18	LHCLK
3	IO_L08N_3/LHCLK7	P21	LHCLK
3	IO_L08P_3/TRDY2/LHCLK6	P19	LHCLK
3	IO_L09N_3	P25	I/O
3	IO_L09P_3	P24	I/O
3	IO_L10N_3	P29	I/O

Table 66: Spartan-3A TQ144 Pinout(Continued)

Bank	Pin Name	Pin	Type
3	IO_L10P_3	P27	I/O
3	IO_L11N_3	P30	I/O
3	IO_L11P_3	P28	I/O
3	IO_L12N_3	P32	I/O
3	IO_L12P_3	P31	I/O
3	IP_L13N_3/VREF_3	P35	VREF
3	IP_L13P_3	P33	INPUT
3	VCCO_3	P14	VCCO
3	VCCO_3	P23	VCCO
GND	GND	P9	GND
GND	GND	P17	GND
GND	GND	P26	GND
GND	GND	P34	GND
GND	GND	P56	GND
GND	GND	P65	GND
GND	GND	P81	GND
GND	GND	P89	GND
GND	GND	P100	GND
GND	GND	P106	GND
GND	GND	P118	GND
GND	GND	P128	GND
GND	GND	P137	GND
VCCAUX	SUSPEND	P74	PWR MGMT
VCCAUX	DONE	P73	CONFIG
VCCAUX	PROG_B	P144	CONFIG
VCCAUX	TCK	P109	JTAG
VCCAUX	TDI	P2	JTAG
VCCAUX	TDO	P107	JTAG
VCCAUX	TMS	P1	JTAG
VCCAUX	VCCAUX	P36	VCCAUX
VCCAUX	VCCAUX	P66	VCCAUX
VCCAUX	VCCAUX	P108	VCCAUX
VCCAUX	VCCAUX	P133	VCCAUX
VCCINT	VCCINT	P22	VCCINT
VCCINT	VCCINT	P52	VCCINT
VCCINT	VCCINT	P94	VCCINT
VCCINT	VCCINT	P122	VCCINT

Table 69: Spartan-3A FT256 Pinout (XC3S700A,

Bank	XC3S700A XC3S1400A	FT256 Ball	Type
1	IO_L20P_1/A18	E14	DUAL
1	IO_L22N_1/A21	D15	DUAL
1	IO_L22P_1/A20	D16	DUAL
1	IO_L23N_1/A23	D14	DUAL
1	IO_L23P_1/A22	E13	DUAL
1	IO_L24N_1/A25	C15	DUAL
1	IO_L24P_1/A24	C16	DUAL
1	IP_1/VREF_1	H12	VREF
1	IP_1/VREF_1	J14	VREF
1	IP_1/VREF_1	M13	VREF
1	IP_1/VREF_1	M14	VREF
1	VCCO_1	E15	VCCO
1	VCCO_1	J15	VCCO
1	VCCO_1	N15	VCCO
2	IO_L01N_2/M0	P4	DUAL
2	IO_L01P_2/M1	N4	DUAL
2	IO_L02N_2/CSO_B	T2	DUAL
2	IO_L02P_2/M2	R2	DUAL
2	IO_L03N_2/VS2	T3	DUAL
2	IO_L03P_2/RDWR_B	R3	DUAL
2	IO_L04N_2/VS0	P5	DUAL
2	IO_L04P_2/VS1	N6	DUAL
2	IO_L05N_2	R5	I/O
2	IO_L05P_2	T4	I/O
2	IO_L06N_2/D6	T6	DUAL
2	IO_L06P_2/D7	T5	DUAL
2	IO_L08N_2/D4	N8	DUAL
2	IO_L08P_2/D5	P7	DUAL
2	IO_L09N_2/GCLK13	T7	GCLK
2	IO_L09P_2/GCLK12	R7	GCLK
2	IO_L10N_2/GCLK15	T8	GCLK
2	IO_L10P_2/GCLK14	P8	GCLK
2	IO_L11N_2/GCLK1	P9	GCLK
2	IO_L11P_2/GCLK0	N9	GCLK
2	IO_L12N_2/GCLK3	T9	GCLK
2	IO_L12P_2/GCLK2	R9	GCLK
2	IO_L14N_2/MOSI/CSI_B	P10	DUAL
2	IO_L14P_2	T10	I/O
2	IO_L15N_2/DOUT	R11	DUAL
2	IO_L15P_2/AWAKE	T11	PWRMGT

Table 69: Spartan-3A FT256 Pinout (XC3S700A,

Bank	XC3S700A XC3S1400A	FT256 Ball	Type
2	IO_L16N_2	N11	I/O
2	IO_L16P_2	P11	I/O
2	IO_L17N_2/D3	P12	DUAL
2	IO_L17P_2/INIT_B	T12	DUAL
2	IO_L18N_2/D1	R13	DUAL
2	IO_L18P_2/D2	T13	DUAL
2	IO_L19N_2	P13	I/O
2	IO_L19P_2	N12	I/O
2	IO_L20N_2/CCLK	R14	DUAL
2	IO_L20P_2/D0/DIN/MISO	T14	DUAL
2	IP_2/VREF_2	M11	VREF
2	IP_2/VREF_2	M7	VREF
2	IP_2/VREF_2	M9	VREF
2	IP_2/VREF_2	N5	VREF
2	IP_2/VREF_2	P6	VREF
2	VCCO_2	R12	VCCO
2	VCCO_2	R4	VCCO
2	VCCO_2	R8	VCCO
3	IO_L01N_3	C1	I/O
3	IO_L01P_3	C2	I/O
3	IO_L02N_3	D3	I/O
3	IO_L02P_3	D4	I/O
3	IO_L03N_3	E1	I/O
3	IO_L03P_3	D1	I/O
3	IO_L04N_3	F4	I/O
3	IO_L04P_3	E4	I/O
3	IO_L05N_3	E2	I/O
3	IO_L05P_3	E3	I/O
3	IO_L07N_3	G3	I/O
3	IO_L07P_3	F3	I/O
3	IO_L08N_3/VREF_3	G1	VREF
3	IO_L08P_3	F1	I/O
3	IO_L11N_3/LHCLK1	H1	LHCLK
3	IO_L11P_3/LHCLK0	G2	LHCLK
3	IO_L12N_3/IRDY2/LHCLK3	J3	LHCLK
3	IO_L12P_3/LHCLK2	H3	LHCLK
3	IO_L14N_3/LHCLK5	J1	LHCLK
3	IO_L14P_3/LHCLK4	J2	LHCLK
3	IO_L15N_3/LHCLK7	K1	LHCLK
3	IO_L15P_3/TRDY2/LHCLK6	K3	LHCLK

XC3S50A Differential I/O Alignment Differences

Also, some differential I/O pairs on the XC3S50A FPGA are aligned differently than the corresponding pairs on the XC3S200A or XC3S400A FPGAs, as shown in [Table 74](#). All the mismatched pairs are in I/O Bank 2. The shading highlights the N side of each pair.

Table 74: Differential I/O Differences in FT256

FT256 Ball	Bank	XC3S50A	XC3S200A XC3S400A
T3	2	IO_L04P_2/VS2	IO_L03N_2/VS2
N6		IO_L03N_2/VS1	IO_L04P_2/VS1
R5		IO_L06P_2	IO_L05N_2
T5		IO_L05N_2/D7	IO_L06P_2/D7
P10		IO_L14P_2/MOSI /CSI_B	IO_L14N_2/MOSI /CSI_B
T10		IO_L14N_2	IO_L14P_2
R13		IO_L20P_2	IO_L18N_2
T14		IO_L18N_2	IO_L20P_2

XC3S50A Does Not Have BPI Mode Address Outputs

The XC3S50A FPGA does not generate the BPI-mode address pins during configuration. [Table 75](#) summarizes these differences.

Table 75: XC3S50A BPI Functional Differences

FT256 Ball	Bank	XC3S50A	XC3S200A XC3S400A
N16	1	IO_L03N_1	IO_L03N_1/A1
P16		IO_L03P_1	IO_L03P_1/A0
J13		IO_L10N_1	IO_L10N_1/A9
J12		IO_L10P_1	IO_L10P_1/A8
F13		IO_L20N_1	IO_L20N_1/A19
E14		IO_L20P_1	IO_L20P_1/A18
D15		IO_L22N_1	IO_L22N_1/A21
D16		IO_L22P_1	IO_L22P_1/A20
D14		IO_L23N_1	IO_L23N_1/A23
E13		IO_L23P_1	IO_L23P_1/A22
C15		IO_L24N_1	IO_L24N_1/A25
C16		IO_L24P_1	IO_L24P_1/A24

Table 77: Spartan-3A FG320 Pinout(*Continued*)

Bank	Pin Name	FG320 Ball	Type
GND	GND	R15	GND
GND	GND	T9	GND
GND	GND	V1	GND
GND	GND	V7	GND
GND	GND	V12	GND
GND	GND	V18	GND
VCCAUX	SUSPEND	T16	PWR MGMT
VCCAUX	DONE	V17	CONFIG
VCCAUX	PROG_B	C4	CONFIG
VCCAUX	TCK	A17	JTAG
VCCAUX	TDI	E4	JTAG
VCCAUX	TDO	E14	JTAG
VCCAUX	TMS	C3	JTAG
VCCAUX	VCCAUX	A9	VCCAUX
VCCAUX	VCCAUX	G10	VCCAUX
VCCAUX	VCCAUX	J12	VCCAUX
VCCAUX	VCCAUX	J18	VCCAUX
VCCAUX	VCCAUX	K1	VCCAUX
VCCAUX	VCCAUX	K7	VCCAUX
VCCAUX	VCCAUX	M10	VCCAUX
VCCAUX	VCCAUX	V10	VCCAUX
VCCINT	VCCINT	H9	VCCINT
VCCINT	VCCINT	H11	VCCINT
VCCINT	VCCINT	J8	VCCINT
VCCINT	VCCINT	K11	VCCINT
VCCINT	VCCINT	L8	VCCINT
VCCINT	VCCINT	L10	VCCINT

FG400: 400-ball Fine-pitch Ball Grid Array

The 400-ball fine-pitch ball grid array, FG400, supports two different Spartan-3A FPGAs, the XC3S400A and the XC3S700A. Both devices share a common footprint for this package as shown in [Table 81](#) and [Figure 24](#).

[Table 81](#) lists all the FG400 package pins. They are sorted by bank number and then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at

www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip

Pinout Table

[Table 81: Spartan-3A FG400 Pinout](#)

Bank	Pin Name	FG400 Ball	Type
0	IO_L01N_0	A18	I/O
0	IO_L01P_0	B18	I/O
0	IO_L02N_0	C17	I/O
0	IO_L02P_0/VREF_0	D17	VREF
0	IO_L03N_0	E15	I/O
0	IO_L03P_0	D16	I/O
0	IO_L04N_0	A17	I/O
0	IO_L04P_0/VREF_0	B17	VREF
0	IO_L05N_0	A16	I/O
0	IO_L05P_0	C16	I/O
0	IO_L06N_0	C15	I/O
0	IO_L06P_0	D15	I/O
0	IO_L07N_0	A14	I/O
0	IO_L07P_0	C14	I/O
0	IO_L08N_0	A15	I/O
0	IO_L08P_0	B15	I/O
0	IO_L09N_0	F13	I/O
0	IO_L09P_0	E13	I/O
0	IO_L10N_0/VREF_0	C13	VREF
0	IO_L10P_0	D14	I/O
0	IO_L11N_0	C12	I/O
0	IO_L11P_0	B13	I/O
0	IO_L12N_0	F12	I/O
0	IO_L12P_0	D12	I/O
0	IO_L13N_0	A12	I/O

[Table 81: Spartan-3A FG400 Pinout\(Continued\)](#)

Bank	Pin Name	FG400 Ball	Type
0	IO_L13P_0	B12	I/O
0	IO_L14N_0	C11	I/O
0	IO_L14P_0	B11	I/O
0	IO_L15N_0/GCLK5	E11	GCLK
0	IO_L15P_0/GCLK4	D11	GCLK
0	IO_L16N_0/GCLK7	C10	GCLK
0	IO_L16P_0/GCLK6	A10	GCLK
0	IO_L17N_0/GCLK9	E10	GCLK
0	IO_L17P_0/GCLK8	D10	GCLK
0	IO_L18N_0/GCLK11	A8	GCLK
0	IO_L18P_0/GCLK10	A9	GCLK
0	IO_L19N_0	C9	I/O
0	IO_L19P_0	B9	I/O
0	IO_L20N_0	C8	I/O
0	IO_L20P_0	B8	I/O
0	IO_L21N_0	D8	I/O
0	IO_L21P_0	C7	I/O
0	IO_L22N_0/VREF_0	F9	VREF
0	IO_L22P_0	E9	I/O
0	IO_L23N_0	F8	I/O
0	IO_L23P_0	E8	I/O
0	IO_L24N_0	A7	I/O
0	IO_L24P_0	B7	I/O
0	IO_L25N_0	C6	I/O
0	IO_L25P_0	A6	I/O
0	IO_L26N_0	B5	I/O
0	IO_L26P_0	A5	I/O
0	IO_L27N_0	F7	I/O
0	IO_L27P_0	E7	I/O
0	IO_L28N_0	D6	I/O
0	IO_L28P_0	C5	I/O
0	IO_L29N_0	C4	I/O
0	IO_L29P_0	A4	I/O
0	IO_L30N_0	B3	I/O
0	IO_L30P_0	A3	I/O
0	IO_L31N_0	F6	I/O
0	IO_L31P_0	E6	I/O
0	IO_L32N_0/PUDC_B	B2	DUAL

Table 81: Spartan-3A FG400 Pinout(Continued)

Bank	Pin Name	FG400 Ball	Type
1	IP_1/VREF_1	N14	VREF
1	IP_L04N_1/VREF_1	P15	VREF
1	IP_L04P_1	P14	INPUT
1	IP_L11N_1/VREF_1	M15	VREF
1	IP_L11P_1	M16	INPUT
1	IP_L15N_1	M13	INPUT
1	IP_L15P_1/VREF_1	M14	VREF
1	IP_L19N_1	L13	INPUT
1	IP_L19P_1	L14	INPUT
1	IP_L23N_1	K14	INPUT
1	IP_L23P_1/VREF_1	K15	VREF
1	IP_L27N_1	J15	INPUT
1	IP_L27P_1	J16	INPUT
1	IP_L31N_1	J13	INPUT
1	IP_L31P_1/VREF_1	J14	VREF
1	IP_L35N_1	H14	INPUT
1	IP_L35P_1	H15	INPUT
1	IP_L39N_1	G14	INPUT
1	IP_L39P_1/VREF_1	G15	VREF
1	VCCO_1	D19	VCCO
1	VCCO_1	H16	VCCO
1	VCCO_1	K19	VCCO
1	VCCO_1	N16	VCCO
1	VCCO_1	T19	VCCO
2	IO_L01N_2/M0	V4	DUAL
2	IO_L01P_2/M1	U4	DUAL
2	IO_L02N_2/CSO_B	Y2	DUAL
2	IO_L02P_2/M2	W3	DUAL
2	IO_L03N_2	W4	I/O
2	IO_L03P_2	Y3	I/O
2	IO_L04N_2	R7	I/O
2	IO_L04P_2	T6	I/O
2	IO_L05N_2	U5	I/O
2	IO_L05P_2	V5	I/O
2	IO_L06N_2	U6	I/O
2	IO_L06P_2	T7	I/O
2	IO_L07N_2/VS2	U7	DUAL
2	IO_L07P_2/RDWR_B	T8	DUAL
2	IO_L08N_2	Y5	I/O
2	IO_L08P_2	Y4	I/O

Table 81: Spartan-3A FG400 Pinout(Continued)

Bank	Pin Name	FG400 Ball	Type
2	IO_L09N_2/VS0	W6	DUAL
2	IO_L09P_2/VS1	V6	DUAL
2	IO_L10N_2	Y7	I/O
2	IO_L10P_2	Y6	I/O
2	IO_L11N_2	U9	I/O
2	IO_L11P_2	T9	I/O
2	IO_L12N_2/D6	W8	DUAL
2	IO_L12P_2/D7	V7	DUAL
2	IO_L13N_2	V9	I/O
2	IO_L13P_2	V8	I/O
2	IO_L14N_2/D4	T10	DUAL
2	IO_L14P_2/D5	U10	DUAL
2	IO_L15N_2/GCLK13	Y9	GCLK
2	IO_L15P_2/GCLK12	W9	GCLK
2	IO_L16N_2/GCLK15	W10	GCLK
2	IO_L16P_2/GCLK14	V10	GCLK
2	IO_L17N_2/GCLK1	V11	GCLK
2	IO_L17P_2/GCLK0	Y11	GCLK
2	IO_L18N_2/GCLK3	V12	GCLK
2	IO_L18P_2/GCLK2	U11	GCLK
2	IO_L19N_2	R12	I/O
2	IO_L19P_2	T12	I/O
2	IO_L20N_2/MOSI/CSI_B	W12	DUAL
2	IO_L20P_2	Y12	I/O
2	IO_L21N_2	W13	I/O
2	IO_L21P_2	Y13	I/O
2	IO_L22N_2/DOUT	V13	DUAL
2	IO_L22P_2/AWAKE	U13	PWR MGMT
2	IO_L23N_2	R13	I/O
2	IO_L23P_2	T13	I/O
2	IO_L24N_2/D3	W14	DUAL
2	IO_L24P_2/INIT_B	Y14	DUAL
2	IO_L25N_2	T14	I/O
2	IO_L25P_2	V14	I/O
2	IO_L26N_2/D1	V15	DUAL
2	IO_L26P_2/D2	Y15	DUAL
2	IO_L27N_2	T15	I/O
2	IO_L27P_2	U15	I/O
2	IO_L28N_2	W16	I/O

FG484: 484-ball Fine-pitch Ball Grid Array

The 484-ball fine-pitch ball grid array, FG484, supports both the XC3S700A and the XC3S1400A FPGAs. There are three pinout differences, as described in [Table 86](#).

[Table 83](#) lists all the FG484 package pins. They are sorted by bank number and then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

The shaded rows indicate pinout differences between the XC3S700A and the XC3S1400A FPGAs. The XC3S700A has three unconnected balls, indicated as N.C. (No Connection) in [Table 83](#) and with the black diamond character (◆) in [Table 83](#) and [Figure 25](#).

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at

www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip.

Pinout Table

[Table 83: Spartan-3A FG484 Pinout](#)

Bank	Pin Name	FG484 Ball	Type
0	IO_L01N_0	D18	I/O
0	IO_L01P_0	E17	I/O
0	IO_L02N_0	C19	I/O
0	IO_L02P_0/VREF_0	D19	VREF
0	IO_L03N_0	A20	I/O
0	IO_L03P_0	B20	I/O
0	IO_L04N_0	F15	I/O
0	IO_L04P_0	E15	I/O
0	IO_L05N_0	A18	I/O
0	IO_L05P_0	C18	I/O
0	IO_L06N_0	A19	I/O
0	IO_L06P_0/VREF_0	B19	VREF
0	IO_L07N_0	C17	I/O
0	IO_L07P_0	D17	I/O
0	IO_L08N_0	C16	I/O
0	IO_L08P_0	D16	I/O
0	IO_L09N_0	E14	I/O
0	IO_L09P_0	C14	I/O
0	IO_L10N_0	A17	I/O
0	IO_L10P_0	B17	I/O
0	IO_L11N_0	C15	I/O

[Table 83: Spartan-3A FG484 Pinout\(Continued\)](#)

Bank	Pin Name	FG484 Ball	Type
0	IO_L11P_0	D15	I/O
0	IO_L12N_0/VREF_0	A15	VREF
0	IO_L12P_0	A16	I/O
0	IO_L13N_0	A14	I/O
0	IO_L13P_0	B15	I/O
0	IO_L14N_0	E13	I/O
0	IO_L14P_0	F13	I/O
0	IO_L15N_0	C13	I/O
0	IO_L15P_0	D13	I/O
0	IO_L16N_0	A13	I/O
0	IO_L16P_0	B13	I/O
0	IO_L17N_0/GCLK5	E12	GCLK
0	IO_L17P_0/GCLK4	C12	GCLK
0	IO_L18N_0/GCLK7	A11	GCLK
0	IO_L18P_0/GCLK6	A12	GCLK
0	IO_L19N_0/GCLK9	C11	GCLK
0	IO_L19P_0/GCLK8	B11	GCLK
0	IO_L20N_0/GCLK11	E11	GCLK
0	IO_L20P_0/GCLK10	D11	GCLK
0	IO_L21N_0	C10	I/O
0	IO_L21P_0	A10	I/O
0	IO_L22N_0	A8	I/O
0	IO_L22P_0	A9	I/O
0	IO_L23N_0	E10	I/O
0	IO_L23P_0	D10	I/O
0	IO_L24N_0/VREF_0	C9	VREF
0	IO_L24P_0	B9	I/O
0	IO_L25N_0	C8	I/O
0	IO_L25P_0	B8	I/O
0	IO_L26N_0	A6	I/O
0	IO_L26P_0	A7	I/O
0	IO_L27N_0	C7	I/O
0	IO_L27P_0	D7	I/O
0	IO_L28N_0	A5	I/O
0	IO_L28P_0	B6	I/O
0	IO_L29N_0	D6	I/O
0	IO_L29P_0	C6	I/O
0	IO_L30N_0	D8	I/O

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
1	IO_L03P_1/A0	AC23	DUAL
1	IO_L04N_1	W21	I/O
1	IO_L04P_1	W20	I/O
1	IO_L05N_1	AC25	I/O
1	IO_L05P_1	AD26	I/O
1	IO_L06N_1	AB26	I/O
1	IO_L06P_1	AC26	I/O
1	IO_L07N_1/VREF_1	AB24	VREF
1	IO_L07P_1	AB23	I/O
1	IO_L08N_1	V19	I/O
1	IO_L08P_1	V18	I/O
1	IO_L09N_1	AA23	I/O
1	IO_L09P_1	AA22	I/O
1	IO_L10N_1	U20	I/O
1	IO_L10P_1	V21	I/O
1	IO_L11N_1	AA25	I/O
1	IO_L11P_1	AA24	I/O
1	IO_L12N_1	U18	I/O
1	IO_L12P_1	U19	I/O
1	IO_L13N_1	Y23	I/O
1	IO_L13P_1	Y22	I/O
1	IO_L14N_1	T20	I/O
1	IO_L14P_1	U21	I/O
1	IO_L15N_1	Y25	I/O
1	IO_L15P_1	Y24	I/O
1	IO_L17N_1	T17	I/O
1	IO_L17P_1	T18	I/O
1	IO_L18N_1	V22	I/O
1	IO_L18P_1	W23	I/O
1	IO_L19N_1	V25	I/O
1	IO_L19P_1	V24	I/O
1	IO_L21N_1	U22	I/O
1	IO_L21P_1	V23	I/O
1	IO_L22N_1	R20	I/O
1	IO_L22P_1	R19	I/O
1	IO_L23N_1/VREF_1	U24	VREF
1	IO_L23P_1	U23	I/O
1	IO_L25N_1/A3	R22	DUAL
1	IO_L25P_1/A2	R21	DUAL
1	IO_L26N_1/A5	T24	DUAL

Table 87: Spartan-3A FG676 Pinout(Continued)

Bank	Pin Name	FG676 Ball	Type
1	IO_L26P_1/A4	T23	DUAL
1	IO_L27N_1/A7	R17	DUAL
1	IO_L27P_1/A6	R18	DUAL
1	IO_L29N_1/A9	R26	DUAL
1	IO_L29P_1/A8	R25	DUAL
1	IO_L30N_1/RHCLK1	P20	RHCLK
1	IO_L30P_1/RHCLK0	P21	RHCLK
1	IO_L31N_1/TRDY1/RHCLK3	P25	RHCLK
1	IO_L31P_1/RHCLK2	P26	RHCLK
1	IO_L33N_1/RHCLK5	N24	RHCLK
1	IO_L33P_1/RHCLK4	P23	RHCLK
1	IO_L34N_1/RHCLK7	N19	RHCLK
1	IO_L34P_1/IRDY1/RHCLK6	P18	RHCLK
1	IO_L35N_1/A11	M25	DUAL
1	IO_L35P_1/A10	M26	DUAL
1	IO_L37N_1	N21	I/O
1	IO_L37P_1	P22	I/O
1	IO_L38N_1/A13	M23	DUAL
1	IO_L38P_1/A12	L24	DUAL
1	IO_L39N_1/A15	N17	DUAL
1	IO_L39P_1/A14	N18	DUAL
1	IO_L41N_1	K26	I/O
1	IO_L41P_1	K25	I/O
1	IO_L42N_1/A17	M20	DUAL
1	IO_L42P_1/A16	N20	DUAL
1	IO_L43N_1/A19	J25	DUAL
1	IO_L43P_1/A18	J26	DUAL
1	IO_L45N_1	M22	I/O
1	IO_L45P_1	M21	I/O
1	IO_L46N_1	K22	I/O
1	IO_L46P_1	K23	I/O
1	IO_L47N_1	M18	I/O
1	IO_L47P_1	M19	I/O
1	IO_L49N_1	J22	I/O
1	IO_L49P_1	J23	I/O
1	IO_L50N_1	K21	I/O
1	IO_L50P_1	L22	I/O
1	IO_L51N_1	G24	I/O
1	IO_L51P_1	G23	I/O
1	IO_L53N_1	K20	I/O

FG676 Footprint

Left Half of FG676 Package (Top View)

313 I/O: Unrestricted, general-purpose user I/O

67 INPUT: Unrestricted, general-purpose input pin

51 DUAL: Configuration pins, then possible user I/O

2 SUSPEND: Dedicated SUSPEND and dual-purpose AWAKE Power Management pins

38 VREF: User I/O or input voltage reference for bank

32 CLK: User I/O, input, or clock buffer input

2 CONFIG: Dedicated configuration pins

4 JTAG: Dedicated JTAG port pins

77 GND: Ground

36 VCCO: Output voltage supply for bank

23 VCCINT: Internal core supply voltage (+1.2V)

14 VCCAUX: Auxiliary supply voltage

17 N.C.: Not connected



Figure 27: FG676 Package Footprint (Top View)

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